NCE N-Channel Super Trench Power MOSFET

Description

The NCEP6050AQU uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g. This device is ideal for high-frequency switching and synchronous rectification.

Application

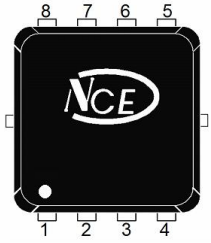
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

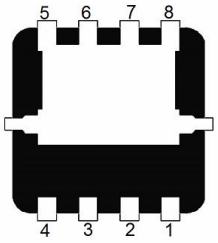
- V_{DS} =60V,I_D =50A
  $R_{DS(ON)}$=6.5mΩ (typical) @ V_{GS}=10V
  $R_{DS(ON)}$=7.7mΩ (typical) @ V_{GS}=4.5V
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 150 °C operating temperature
- Pb-free lead plating

100% UIS TESTED!
100% ΔVds TESTED!

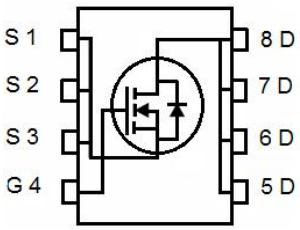
DFN 3.3X3.3



Top View



Bottom View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP6050AQU	NCEP6050AQU	DFN3.3X3.3-8L	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	±20	V
Drain Current-Continuous		I_D	50	A
Drain Current-Continuous(T_C=100℃)		I_D (100℃)	39	A
Pulsed Drain Current		I_{DM}	200	A
Maximum Power Dissipation		P_D	60	W
Derating factor			0.48	W/℃
Single pulse avalanche energy (Note 5)		E_{AS}	350	mJ
V_{DS} Spike (Note 6)	10μs	72		V
Operating Junction and Storage Temperature Range		T_J,T_{STG}	-55 To 150	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	$R_{\theta JC}$	2.1	℃/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	60		-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=60V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	1.2	1.8	2.4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=25A	-	6.5	7.5	mΩ
		V_{GS}=4.5V, I_D=25A	-	7.7	8.8	
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=25A		60	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{lss}	V_{DS}=30V,V_{GS}=0V, F=1.0MHz	-	2000	-	PF
Output Capacitance	C_{oss}		-	315	-	PF
Reverse Transfer Capacitance	C_{rss}		-	9.9	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=30V,I_D=25A V_{GS}=10V,R_G=1.6Ω	-	8	-	nS
Turn-on Rise Time	t_r		-	2	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	29	-	nS
Turn-Off Fall Time	t_f		-	4	-	nS
Total Gate Charge	Q_g	V_{DS}=30V,I_D=25A, V_{GS}=10V	-	34.8	-	nC
Gate-Source Charge	Q_{gs}		-	7		nC
Gate-Drain Charge	Q_{gd}		-	5.3		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=25A	-		1.2	V
Diode Forward Current (Note 2)	I_S		-	-	50	A
Reverse Recovery Time	t_{rr}	T_J = 25°C, I_F =25A di/dt = 100A/μs(Note3)	-	38	-	nS
Reverse Recovery Charge	Qrr		-	48	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition : Tj=25℃,V_{DD}=30V,V_G=10V,L=0.5mH,Rg=25Ω
6. The spike duty cycle 5% max, limited by junction temperature T_J(MAX)=125° C.

Typical Electrical and Thermal Characteristics

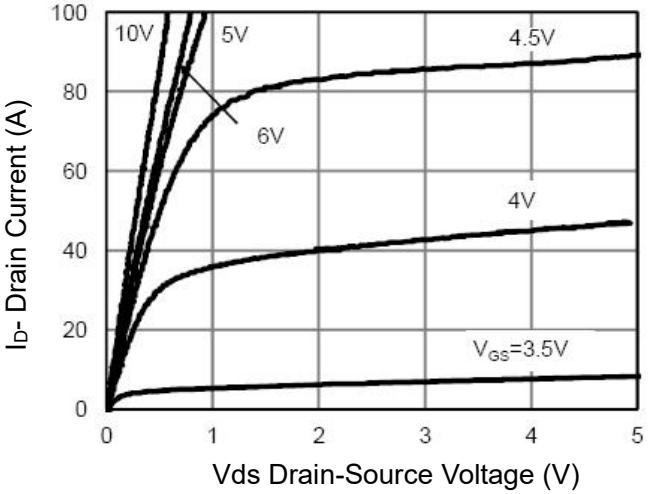


Figure 1 Output Characteristics

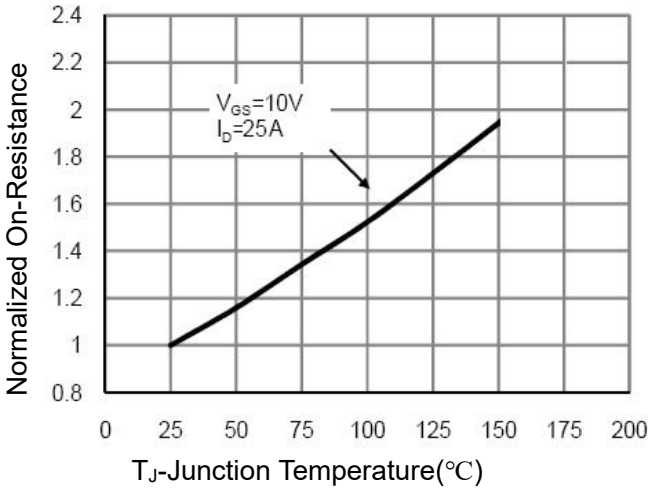


Figure 4 Rdson-Junction Temperature

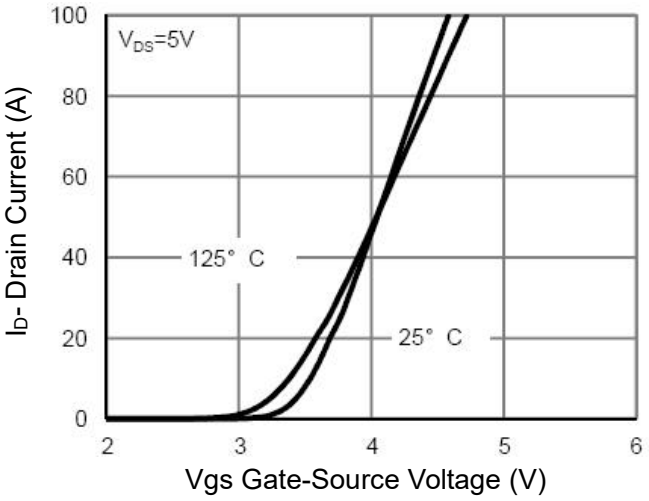


Figure 2 Transfer Characteristics

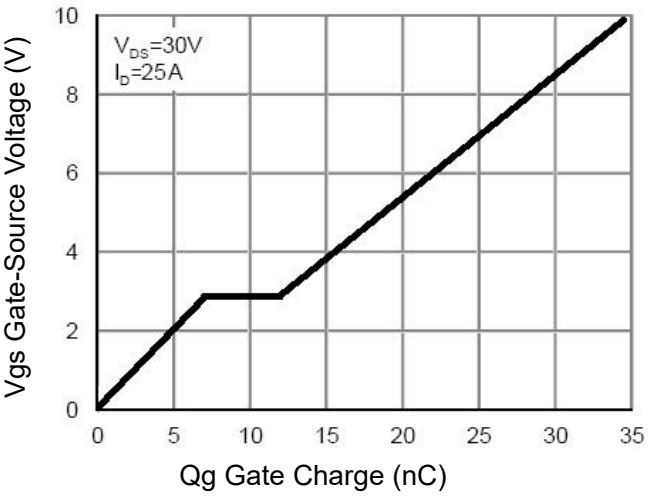


Figure 5 Gate Charge

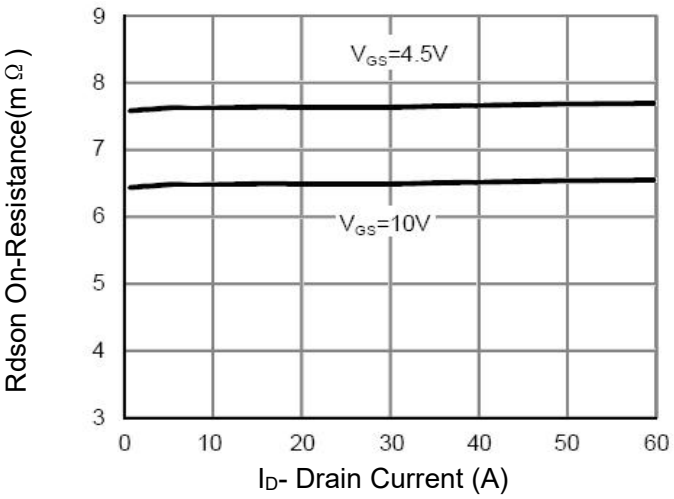


Figure 3 Rdson- Drain Current

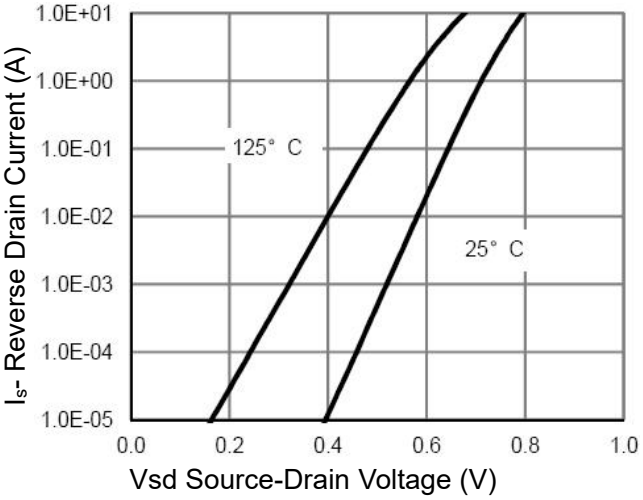


Figure 6 Source- Drain Diode Forward

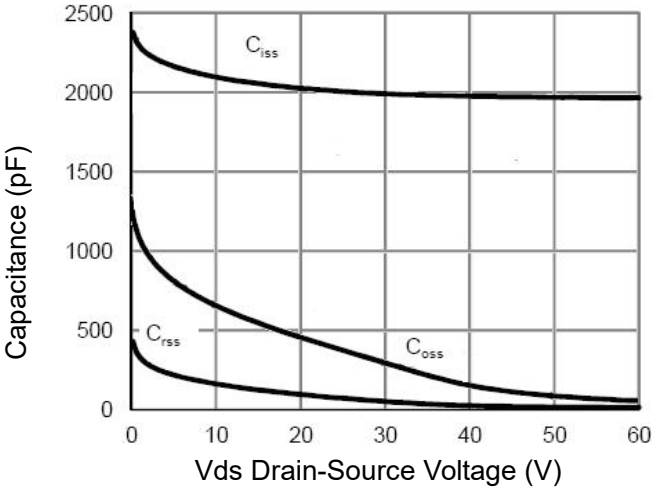


Figure 7 Capacitance vs Vds

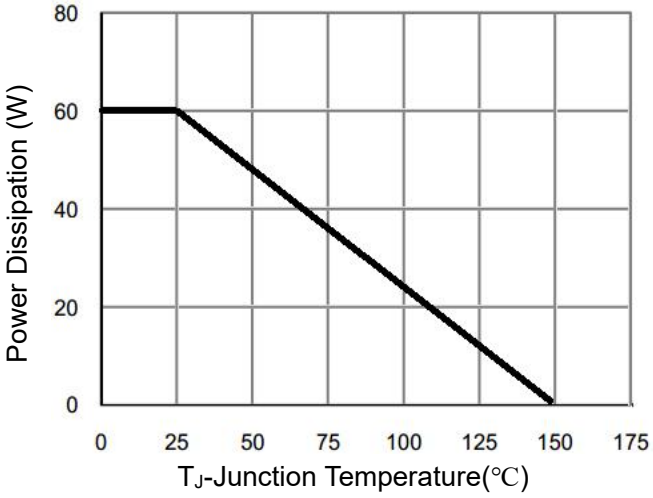


Figure 9 Power De-rating

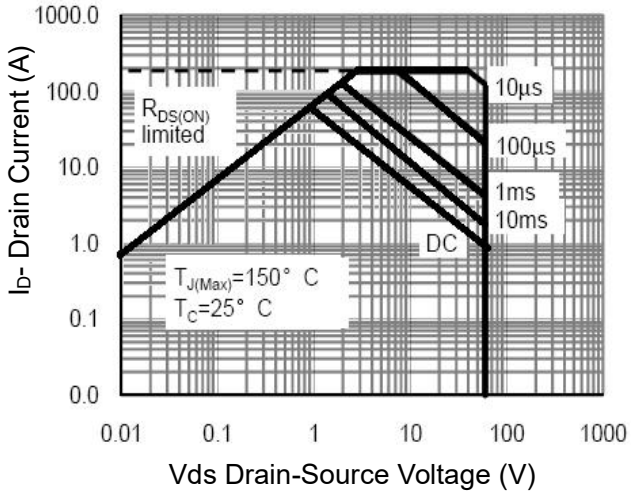


Figure 8 Safe Operation Area

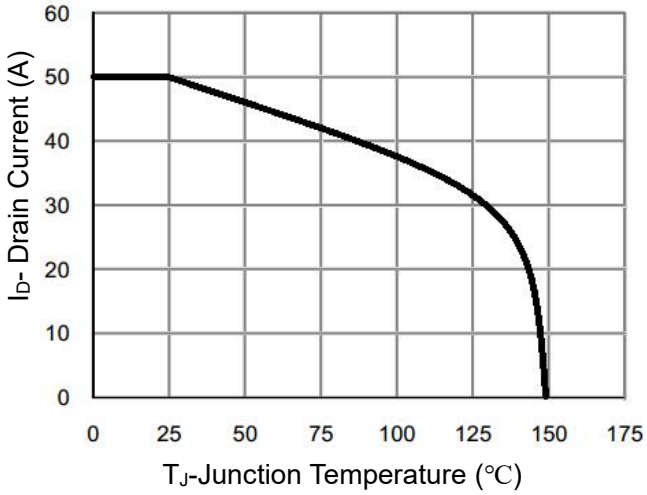


Figure 10 Current De-rating

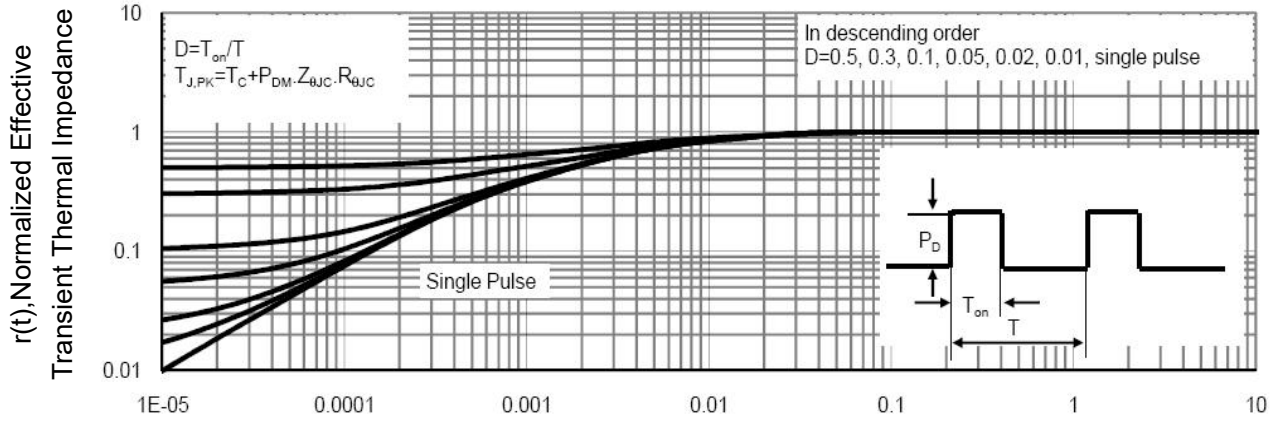
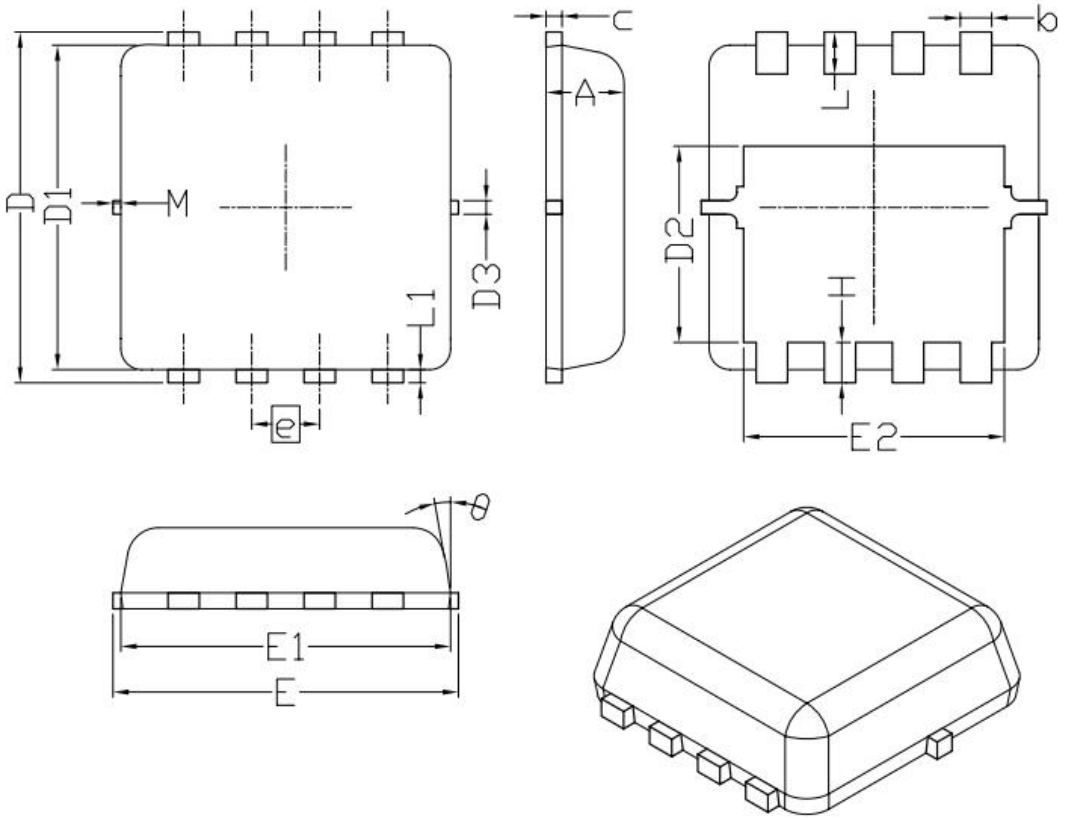
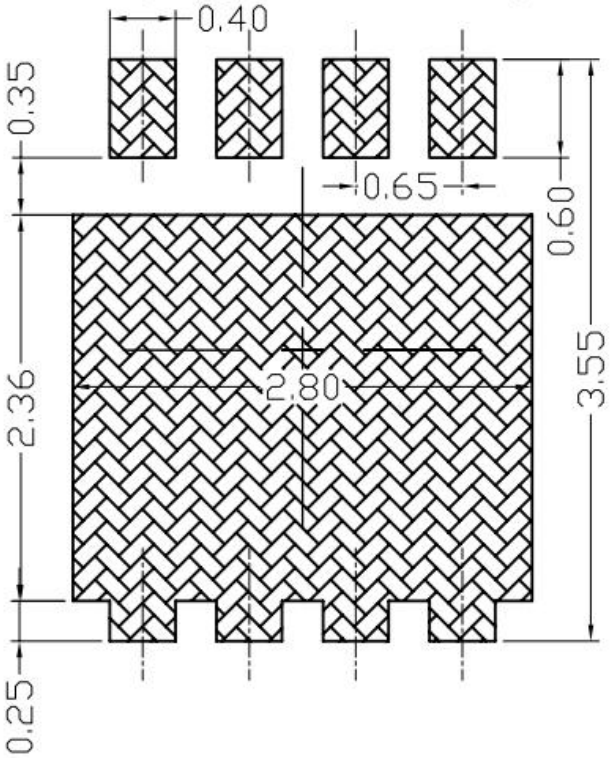


Figure 11 Normalized Maximum Transient Thermal Impedance

DFN3.3X3.3-8L Package Information



Land Pattern
(Only for Reference)



SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	---	0.13	---
E	3.10	3.20	3.30
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	---	0.13	---
θ	---	10°	12°
M	*	*	0.15
* Not specified			

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